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**Semiconductor devices - Mechanical and climatic test methods -
Part 24: Accelerated moisture resistance - Unbiased HAST**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**Semiconductor devices - Mechanical and climatic test methods -
Part 24: Accelerated moisture resistance - Unbiased HAST**

FOREWORD

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IEC 60749-24 has been prepared by IEC technical committee 47: Semiconductor devices. It is an International Standard.

This second edition, cancels and replaces the first edition published in 2004. It is based on JEDEC document JESD22-A118B.01. It is used with permission of the copyright holder, JEDEC Solid State Technology Association. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) rearrangement of clauses to reposition requirements;
- b) addition of two notes to the post-test electrical procedures.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47/2957/FDIS	47/2974/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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